

# **BUK6607-75C**

## N-channel TrenchMOS FET

Rev. 2 — 17 November 2010

Product data sheet

### 1. Product profile

### 1.1 General description

Intermediate level gate drive N-channel enhancement mode Field-Effect Transistor (FET) in a plastic package using advanced TrenchMOS technology. This product has been designed and qualified to the appropriate AEC Q101 standard for use in high performance automotive applications.

#### 1.2 Features and benefits

- AEC Q101 compliant
- Suitable for intermediate level gate drive sources
- Suitable for thermally demanding environments due to 175 °C rating

### 1.3 Applications

- 12 V and 24 V Automotive systems
- Electric and electro-hydraulic power steering
- Motors, lamps and solenoid control
- Start-Stop micro-hybrid applications
- Transmission control
- Ultra high performance power switching

### 1.4 Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions		Min	Тур	Max	Unit
$V_{DS}$	drain-source voltage	$T_j \ge 25 ^{\circ}\text{C}; T_j \le 175 ^{\circ}\text{C}$		-	-	75	V
I <sub>D</sub>	drain current	$V_{GS} = 10 \text{ V}; T_{mb} = 25 \text{ °C};$ see Figure 1	[1]	-	-	100	Α
P <sub>tot</sub>	total power dissipation	T <sub>mb</sub> = 25 °C; see <u>Figure 2</u>		-	-	204	W
Static characteristics							
R <sub>DSon</sub>	drain-source on-state resistance	$V_{GS} = 10 \text{ V}; I_D = 25 \text{ A};$ $T_j = 25 \text{ °C}; \text{ see } \frac{\text{Figure 11}}{\text{ or } 100 \text{ c}}$		-	6	7	mΩ



Table 1. Quick reference data ...continued

Symbol	Parameter	Conditions	Min	Тур	Max	Unit	
Avalanche ruggedness							
E <sub>DS(AL)S</sub>	non-repetitive drain-source avalanche energy	$I_D$ = 100 A; $V_{sup} \le 75$ V; $R_{GS}$ = 50 $\Omega$ ; $V_{GS}$ = 10 V; $T_{j(init)}$ = 25 °C; unclamped	-	-	191	mJ	
Dynamic o	characteristics						
$Q_{GD}$	gate-drain charge	$I_D = 25 \text{ A}; V_{DS} = 60 \text{ V};$ $V_{GS} = 10 \text{ V}; \text{ see } \frac{\text{Figure } 13}{\text{Figure } 14};$	-	35	-	nC	

<sup>[1]</sup> Continuous current is limited by package.

### 2. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol		
1	G	gate				
2	D	Drain	mb			
3	S	source				
mb	D	mounting base; connected to drain		mbb076 S		
			SOT404 (D2PAK)			

## 3. Ordering information

Table 3. Ordering information

Type number	Package	<del>;</del>				
	Name	Description	Version			
BUK6607-75C	D2PAK	plastic single-ended surface-mounted package (D2PAK); 3 leads (one lead cropped)	SOT404			

## 4. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
$V_{DS}$	drain-source voltage	T <sub>j</sub> ≥ 25 °C; T <sub>j</sub> ≤ 175 °C		-	75	V
V <sub>GS</sub>	gate-source voltage	DC	[1]	-16	16	٧
		Pulsed	[2]	-20	20	٧
$I_D$	drain current	$T_{mb}$ = 25 °C; $V_{GS}$ = 10 V; see <u>Figure 1</u>	[3]	-	100	Α
		$T_{mb}$ = 100 °C; $V_{GS}$ = 10 V; see Figure 1	[3]	-	75	Α
I <sub>DM</sub>	peak drain current	$T_{mb}$ = 25 °C; $t_p \le 10 \mu s$ ; pulsed; see <u>Figure 3</u>		-	423	Α
P <sub>tot</sub>	total power dissipation	T <sub>mb</sub> = 25 °C; see <u>Figure 2</u>		-	204	W
T <sub>stg</sub>	storage temperature			-55	175	°C
T <sub>j</sub>	junction temperature			-55	175	°C
Source-drain	diode					
Is	source current	T <sub>mb</sub> = 25 °C	[3]	-	100	Α
I <sub>SM</sub>	peak source current	$t_p \le 10 \ \mu s$ ; pulsed; $T_{mb} = 25 \ ^{\circ}C$		-	423	Α
Avalanche rug	ggedness					
E <sub>DS(AL)S</sub>	non-repetitive drain-source avalanche energy	$I_D$ = 100 A; $V_{sup} \le 75$ V; $R_{GS}$ = 50 $\Omega$ ; $V_{GS}$ = 10 V; $T_{j(init)}$ = 25 °C; unclamped		-	191	mJ
E <sub>DS(AL)R</sub>	repetitive drain-source avalanche energy		[4][5][6]	-	-	J

<sup>[1] -16</sup> V accumulated duration not to exceed 168 hrs.

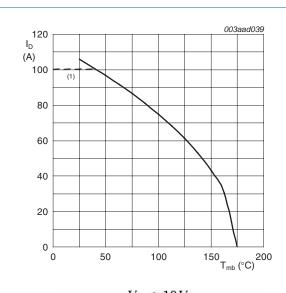
<sup>[2]</sup> Accumulated pulse duration not to exceed 5mins.

<sup>[3]</sup> Continuous current is limited by package.

<sup>[4]</sup> Single-pulse avalanche rating limited by maximum junction temperature of 175  $^{\circ}$ C.

<sup>[5]</sup> Repetitive avalanche rating limited by an average junction temperature of 170 °C.

<sup>[6]</sup> Refer to application note AN10273 for further information.



 $V_{GS} \ge 10 \, V$ (1) Capped at 100 A due to package.

Continuous drain current as a function of mounting base temperature.

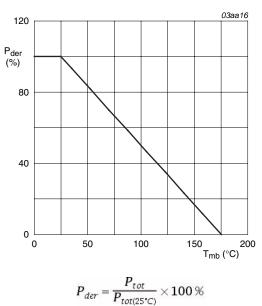
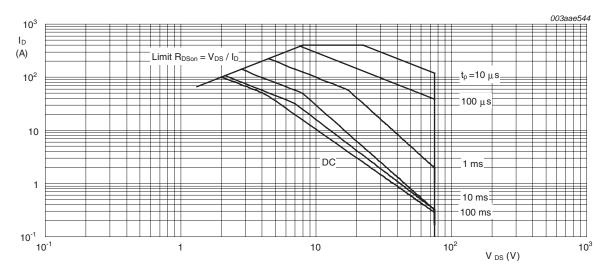


Fig 2. Normalized total power dissipation as a function of mounting base temperature



 $T_{mb} = 25$ °C;  $I_{DM}$  is a single pulse

Fig 3. Safe operating area; continuous and peak drain currents as a function of drain-source voltage

### **Thermal characteristics**

Table 5. **Thermal characteristics** 

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base	see Figure 4	-	-	0.74	K/W

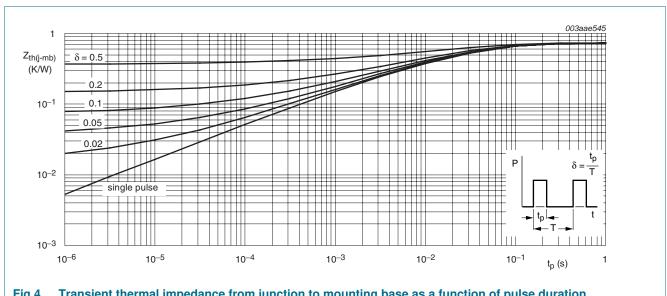


Fig 4. Transient thermal impedance from junction to mounting base as a function of pulse duration

### 6. Characteristics

Table 6. Characteristics

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
Static chara	acteristics					
V <sub>(BR)DSS</sub>	drain-source	$I_D = 250 \ \mu A; \ V_{GS} = 0 \ V; \ T_j = 25 \ ^{\circ}C$	75	-	-	V
	breakdown voltage	$I_D = 250 \ \mu A; \ V_{GS} = 0 \ V; \ T_j = -55 \ ^{\circ}C$	68	-	-	V
V <sub>GS(th)</sub> gate-source thresholds voltage	gate-source threshold voltage	$I_D = 1 \text{ mA}$ ; $V_{DS} = V_{GS}$ ; $T_j = 25 \text{ °C}$ ; see <u>Figure 9</u> ; see <u>Figure 10</u>	1.8	2.3	2.8	V
		$I_D = 1$ mA; $V_{DS} = V_{GS}$ ; $T_j = -55$ °C; see <u>Figure 10</u>	-	-	3.3	V
		$I_D$ = 2.5 mA; $V_{DS}$ = $V_{GS}$ ; $T_j$ = 175 °C; see <u>Figure 10</u>	8.0	-	-	V
I <sub>DSS</sub>	drain leakage current	$V_{DS} = 75 \text{ V}; V_{GS} = 0 \text{ V}; T_j = 175 \text{ °C}$	-	-	500	μΑ
		$V_{DS} = 75 \text{ V}; V_{GS} = 0 \text{ V}; T_j = 25 \text{ °C}$	-	0.02	1	μΑ
$I_{GSS}$	gate leakage current	$V_{DS} = 0 \text{ V}; V_{GS} = 20 \text{ V}; T_j = 25 \text{ °C}$	-	2	100	nA
		$V_{DS} = 0 \text{ V}; V_{GS} = -20 \text{ V}; T_j = 25 \text{ °C}$	-	2	100	nA
R <sub>DSon</sub> drain-source on-state resistance		$V_{GS} = 10 \text{ V}; I_D = 25 \text{ A}; T_j = 25 \text{ °C};$ see <u>Figure 11</u>	-	6	7	mΩ
		$V_{GS} = 4.5 \text{ V}; I_D = 25 \text{ A}; T_j = 25 \text{ °C};$ see Figure 11	-	7.3	9.7	mΩ
		$V_{GS} = 5 \text{ V}; I_D = 25 \text{ A}; T_j = 25 \text{ °C};$ see Figure 11	-	6.9	8.6	mΩ
	$V_{GS}$ = 10 V; $I_D$ = 25 A; $T_j$ = 175 °C; see <u>Figure 12</u> ; see <u>Figure 11</u>	-	-	18.2	mΩ	
Dynamic ch	naracteristics					
Q <sub>G(tot)</sub> total gate charge	total gate charge	$I_D = 25 \text{ A}$ ; $V_{DS} = 60 \text{ V}$ ; $V_{GS} = 10 \text{ V}$ ; see <u>Figure 13</u> ; see <u>Figure 14</u>	-	123	-	nC
		$I_D = 25 \text{ A}$ ; $V_{DS} = 60 \text{ V}$ ; $V_{GS} = 5 \text{ V}$ ; see <u>Figure 13</u> ; see <u>Figure 14</u>	-	69	-	nC
Q <sub>GS</sub>	gate-source charge	$I_D = 25 \text{ A}; V_{DS} = 60 \text{ V}; V_{GS} = 10 \text{ V};$	-	15	-	nC
$Q_GD$	gate-drain charge	see Figure 13; see Figure 14	-	35	-	nC
C <sub>iss</sub>	input capacitance	$V_{GS} = 0 \text{ V}; V_{DS} = 25 \text{ V}; f = 1 \text{ MHz};$	-	5610	7600	рF
C <sub>oss</sub>	output capacitance	T <sub>j</sub> = 25 °C; see <u>Figure 15</u>	-	441	530	рF
C <sub>rss</sub>	reverse transfer capacitance		-	297	410	pF
t <sub>d(on)</sub>	turn-on delay time	$V_{DS}$ = 55 V; $R_L$ = 2.2 $\Omega$ ; $V_{GS}$ = 10 V;	-	24	-	ns
t <sub>r</sub>	rise time	$R_{G(ext)} = 10 \Omega$	-	54	-	ns
t <sub>d(off)</sub>	turn-off delay time		-	247	-	ns
t <sub>f</sub>	fall time		-	110	-	ns
L <sub>D</sub>	internal drain inductance	from upper edge of drain mounting base to centre of die; $T_j = 25$ °C	-	3.5	-	nΗ
L <sub>S</sub>	internal source inductance	from source lead to source bond pad; T <sub>i</sub> = 25 °C	-	7.5	-	nΗ

Table 6. Characteristics ... continued

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
Source-drai	n diode					
V <sub>SD</sub>	source-drain voltage	$I_S = 25 \text{ A}; V_{GS} = 0 \text{ V}; T_j = 25 \text{ °C};$ see <u>Figure 16</u>	-	8.0	1.2	V
t <sub>rr</sub>	reverse recovery time	$I_S = 20 \text{ A}; dI_S/dt = -100 \text{ A}/\mu\text{s}; V_{GS} = 0 \text{ V};$ $V_{DS} = 25 \text{ V}$	-	54	-	ns
Q <sub>r</sub>	recovered charge		-	129	-	nC

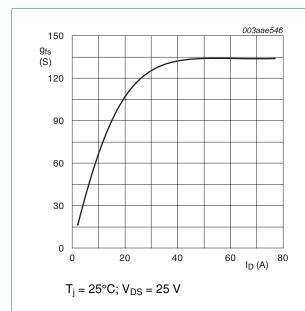


Fig 5. Forward transconductance as a function of drain current; typical values

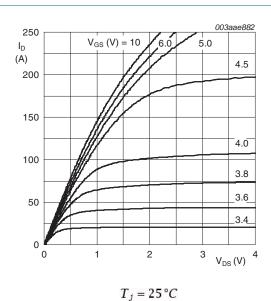
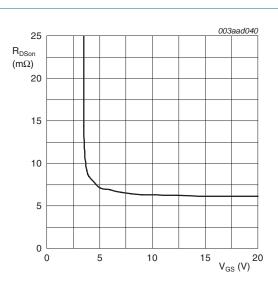
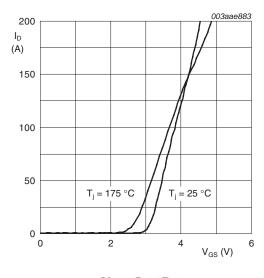


Fig 7. Output characteristics: drain current as a function of drain-source voltage; typical values



 $T_j = 25 \,^{\circ}C; I_D = 25 A$ 

Fig 6. Drain-source on-state resistance as a function of gate-source voltage; typical values



 $V_{DS} > I_D \times R_{DSon}$ 

Fig 8. Transfer characteristics: drain current as a function of gate-source voltage; typical values

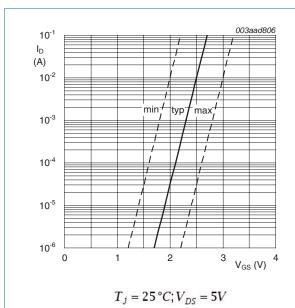


Fig 9. Sub-threshold drain current as a function of gate-source voltage

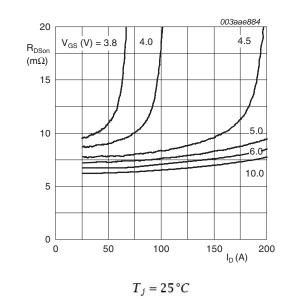
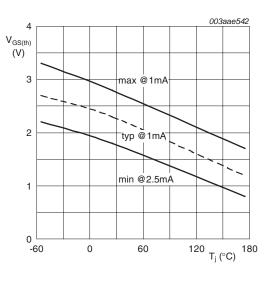


Fig 11. Drain-source on-state resistance as a function of drain current; typical values



 $I_D = 1mA; V_{DS} = V_{GS}$ 

Fig 10. Gate-source threshold voltage as a function of junction temperature

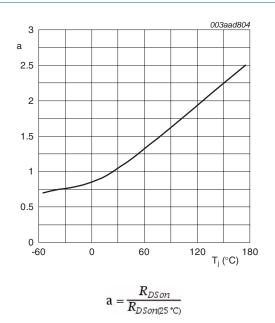


Fig 12. Normalized drain-source on-state resistance factor as a function of junction temperature

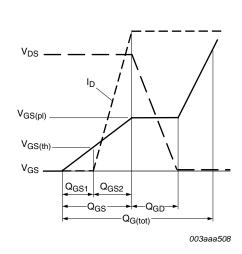


Fig 13. Gate charge waveform definitions

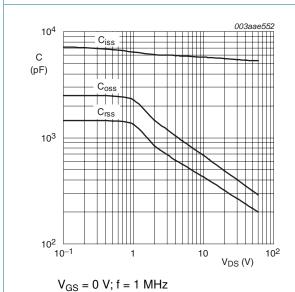
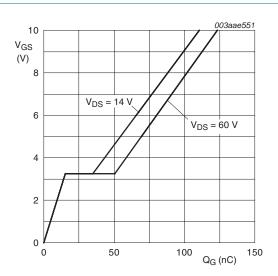
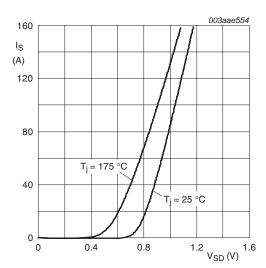


Fig 15. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values



 $T_j = 25^{\circ}C; I_D = 25 A$ 

Fig 14. Gate-source voltage as a function of gate charge; typical values



 $V_{GS} = 0 V$ 

Fig 16. Source (diode forward) current as a function of source-drain (diode forward) voltage; typical values

### 7. Package outline

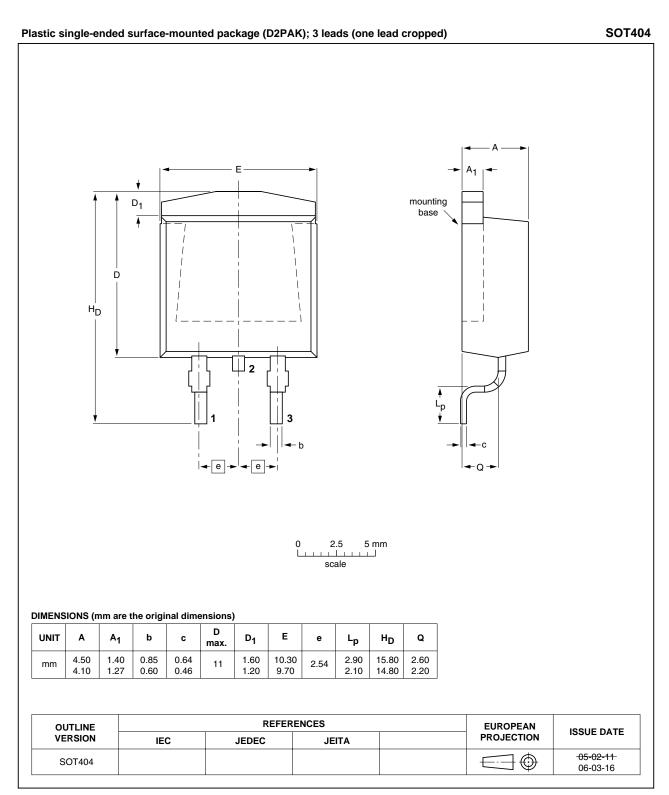


Fig 17. Package outline SOT404 (D2PAK)

## 8. Revision history

### Table 7. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
BUK6607-75C v.2	20101117	Product data sheet	-	BUK6607-75C v.1
Modifications:	<ul> <li>Status change</li> </ul>	ed from objective to product.		
BUK6607-75C v.1	20090323	Objective data sheet	-	-

### 9. Legal information

#### 9.1 Data sheet status

Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

- [1] Please consult the most recently issued document before initiating or completing a design.
- [2] The term 'short data sheet' is explained in section "Definitions"
- [3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL http://www.nexperia.com.

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#### N-channel TrenchMOS FET

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